

What Is Claimed Is:

1. A micromechanical component having a hollow space (10) and a region of porous silicon (11) contiguously thereto, wherein the region of porous silicon (11) is provided for lowering the pressure prevailing in the hollow space (10).
2. The component as recited in Claim 1, wherein a first substrate (20) and a second substrate (30) are provided, an intermediate layer (25, 26, 27) being provided between the first and the second substrates (20, 30).
3. The component as recited in Claim 2, wherein the first and the second substrate (20, 30) are joined to one another in such a way that they are hermetically sealed at the intermediate layer (25, 26, 27).
4. The component as recited in Claim 1, wherein a first substrate (20) and a membrane (60) are provided, the hollow space (10) being provided between the membrane (60) and the first substrate (20), the region of the porous silicon (11) being provided in the first substrate (20).
5. A method for manufacturing a component as recited in one of the preceding claims, wherein, in a first substrate (20), a micromechanical structure (200) is produced; in a second substrate (30), the region of porous silicon (11) is produced; and the first and the second substrates (20, 30) are joined.
6. The method for manufacturing a component as recited in one of Claims 1 through 4, wherein, in a first substrate (20), the region of porous silicon (11) is produced; in the first substrate (20), a micromechanical structure is produced; and a second substrate (30) is joined to the first substrate (20).
7. The method for manufacturing a component as recited in one of Claims 1 through 4, wherein, in a first substrate (20), the region of porous silicon (11) is produced, in the first substrate (20), a micromechanical structure being produced.

8. The method as recited in one of Claims 5, 6 or 7,
wherein the region of porous silicon (11) is activated, and the pressure is thereby lowered.

Abstract

A micromechanical component and a method for producing a micromechanical component are proposed, a hollow space (10) and a region of porous silicon (11) being provided, the region of porous silicon (11) being provided for lowering the pressure prevailing in the

5 hollow space (10).